ABSOCIATION CONNECTING LECTRONICS INDUSTRIES INCOMPACTING OF INTERNATIONAL AND ADDRESS INDUSTRIES INTERNATIONAL AND ADDRESS ADDRESS INTERNATIONAL AND ADDRESS INTERNATIONAL AND ADDRESS	annockburn, Illinois, A	All rights reserved untions.	under both	This docume level parts, t	ent is a declaration er	on of the sub compasses	bstances w all lower l	vithin the manufactur level materials for wh	er listed iter hich the mar	n. Note: if ufacturer	the item is an as has engineering	sembly with lower responsibility.
	1 IPC Web Site for Information on IPC-1752 Standard http://www.ipc.org/IPC-175x Form Type Distribute			*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information							
Supplier Information												
Company name*	ique ID	ue ID U			Unique ID Authority				Response Date*			
onsemi	ai								2024-05-08			
Contact Name	Title - Contact			1	Phone - Contact*				Email - Contact*			
Product-Env-Stewards	wards Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com				
thorized Representative* Title - Representative				Phone - Representative*				Email - Representative*				
Product-Env-Stewards	ro Compliance			NA				Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item Number	Mfr Item Name			Effective Date	Version	Ma	Manufacturing Site		eight*	UOM	Unit Type
	RVHP420MFDWFT 200V/2A PUF DF		FN-8	N-8			M	MY1		49	mg	Each
Manufacturing Proccess Information												
Terminal Plating / Grid Array Material	Terminal Base	Terminal Base Alloy J-ST		Rating	Peak Process Body T		Temperature Max Time at Peak		Temperatur	e Numbe	er of Reflow Cyc	les
Matte Tin (Sn) - annealed	Matte Tin (Sn) - annealed CU Alloy		1		260		С	30	seconds	3		
Comments												
level 1 - maximum time at peak temperature du	ring soldering is 10-3	30 seconds										
For more information regarding material comp	osition please refer t	o page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et					
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted				
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the				
Supplier Digital Signature	astislav Drska	Le							

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	0.34	mg	Supplier	Zinc (Zn)	7440-66-6		0.0004	mg
			Supplier	Iron (Fe)	7439-89-6		0.008	mg
			Supplier	Copper (Cu)	7440-50-8		0.3315	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0001	mg
Die	0.36	mg	Supplier	Silicon (Si)	7440-21-3		0.36	mg
Die Attach Solder	0.82	mg	Supplier	Silver (Ag)	7440-22-4		0.0205	mg
			А	Lead (Pb)	7439-92-1	7a	0.7585	mg
			Supplier	Tin (Sn)	7440-31-5		0.041	mg
Lead Frame	37.39	mg	Supplier	Silver (Ag)	7440-22-4		0.3739	mg
			Supplier	Iron (Fe)	7439-89-6		0.0374	mg
			Supplier	Copper (Cu)	7440-50-8		36.9675	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0112	mg
Mold Compound-Black	48.93	mg		Epoxy resin	proprietary data		3.6698	mg
			Supplier	Phenolic Resin	Proprietary Data		1.2233	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.6698	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2446	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		40.1226	mg
Plating	1.56	mg	Supplier	Tin (Sn)	7440-31-5		1.56	mg
Wire Bond - Cu	0.09	mg	Supplier	Copper (Cu)	7440-50-8		0.09	mg